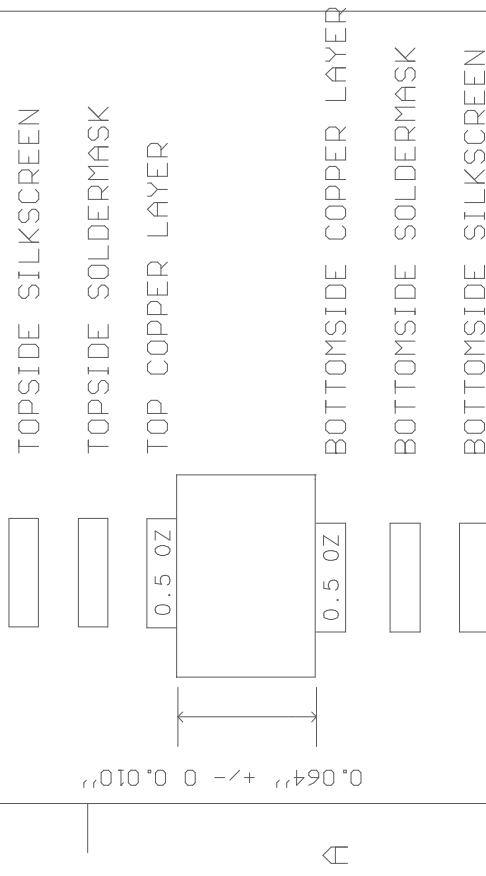


FABRICATION NOTES:

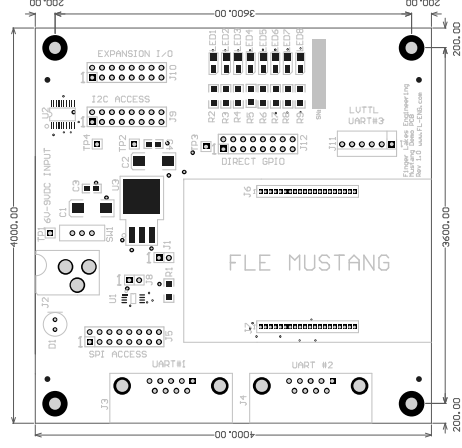
1. MATERIAL LAMINATE MATERIAL GLASS FIBER EPOXY FLAME RETARDANT PER IPC-4101/24, 170C Tg MIN  
PRPREG MATERIAL PER IPC-4101/24 170C Tg MINIMUM SIZE AND CONSTRUCTION PER BOARD LAYOUT
2. COPPER PLATER
  - A. EXTERNAL LAYERS PLATE WITH 0.5oz COPPER ON SURFACE LAYERS PLATE UPTO 1.0oz AFTER COMPLETION
  - B. VIAS AND HOLES COPPER PLATE SHOULD BE NO LESS THAN 0.0007
3. SURFACE FINISH SHOULD BE 60/40 TIN-LEAD
4. MINIMUM TRACE AND SPACE REQUIREMENTS
  - A. WIDTH SHOULD BE MIN 0.008 +/- 0.001
  - B. SPACE SHOULD BE MIN 0.008 +/- 0.001
5. HOLE REQUIREMENTS
  - A. MINIMUM ANNULAR RING - 0.002
  - B. HOLES SHALL BE DRILLED PER NC DATA
6. SOLDERMASK
  - A. SOLDERMASK IS PRESENT ON TOP AND BOTTOM SURFACE
  - B. PCB VENDOR MAY ADJUST PER PROCESS
  - C. ADJUSTMENTS MUST BE AUTHORIZED BY CUSTOMER
7. MARKING
  - A. MARKING SHALL BE PER TOP/BOTTOM SILKSCREEN
  - B. NO SILKSCREEN ALLOWED ON EXPOSED COPPER
  - C. PCB VENDOR MAY ADJUST PER PROCESS
  - D. ADJUSTMENTS MUST BE AUTHORIZED BY CUSTOMER
8. MANUFACTURE TO IPC CLASS-2 STANDARD
9. TESTING
  - A. NO ELECTRICAL/ICT TESTING IS REQUIRED
10. REPAIRS
  - A. NO MODIFICATIONS OR REPAIRS WITHOUT APPROVAL
11. BOW AND TWIST
  - A. SHOULD NOT EXCEED 0.0075 PER INCH
12. CONTROLLED IMPEDANCE LAYERS
  - A. NO CONTROLLED IMPEDANCE REQUIREMENTS
13. TOTAL COPPER LAYERS IS TWO (2)

Board Stackup



ASSEMBLY NOTES:

1. WORKMANSHIP TO MEET IPC CLASS 2 UNLESS NOTED OTHERWISE
2. PCB CONTAINS ELECTROSTATIC SENSITIVE DEVICES - USE STATIC FREE HANDLING
3. DESIGNATORS ARE FOR REFERENCE AND MAY NOT APPEAR ON INDIVIDUAL PARTS
4. ALL THROUGH HOLE COMPONENTS SHOULD BE MOUNTED FLUSH WITH PCB SURFACE UNLESS NOTED OTHERWISE
5. PCB CONTAINS HUMIDITY SENSITIVE COMPONENTS. THESE PARTS MUST BE PLACED AND REFLOWED < 24 HOURS AFTER OPEN AIR EXPOSURE. COMPONENTS THAT HAVE BEEN EXPOSED TO > 20% HUMIDITY MUST BE BAKED PER MANUFACTURER'S INSTRUCTIONS PRIOR TO REFLOW SOLDERING.



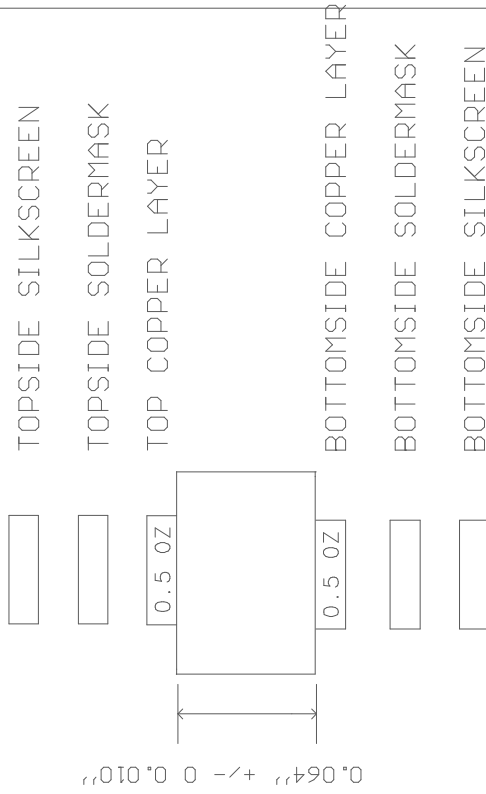
REV	DESCRIPTION	DATE
1.0	Released For Fabrication	07/02/06

Finger Lakes Engineering		Client Contact
INF08FL-ENG.COM		Finger Lakes Engineering
		119 South Cayuga #200
		Ithaca, Ny 14850
SIZE	D	REV
DRAWN BY:	SMS	#99-070206
		1.0
SCALE 1:1		SHEET 1 of 1

**FABRICATION NOTES:**

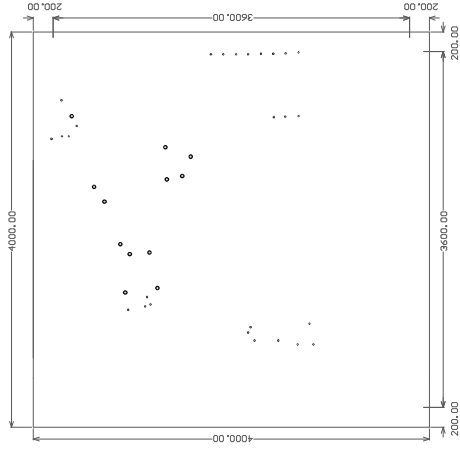
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**Finger Lakes Engineering**  
 INF08FL-ENG.COM

Client Contact  
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 119 South Cayuga #200  
 Ithaca, Ny 14850

SIZE: D DRAWN BY: SMS PART NUMBER: #99-070206 REV: 1.0  
 SCALE: 1:1 SHEET 1 of 1